

# **FMI10N60E**

**FUJI POWER MOSFET** 

# Super FAP-E<sup>3</sup> series

# **N-CHANNEL SILICON POWER MOSFET**

#### ■ Features

Maintains both low power loss and low noise Lower R<sub>DS</sub>(on) characteristic More controllable switching dv/dt by gate resistance Smaller V<sub>GS</sub> ringing waveform during switching Narrow band of the gate threshold voltage (3.0±0.5V) High avalanche durability

## Applications

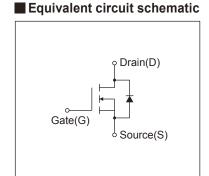
Switching regulators UPS (Uninterruptible Power Supply) DC-DC converters

# Maximum Ratings and Characteristics

# ● Absolute Maximum Ratings at Tc=25°C (unless otherwise specified)

T-Pack(L)	4,5±0,2 1,3±0,2 Fig. 1. (See Notes)
Type name	Fig. 1.
1.2±0.2	Solder Plating Street Name 1
2.54±0.2 0.8'%;? 2.54±0.2	0.4*8;7 2.7±0.2
+ + +       ① ② ③	ONNECTION  ① GATE ② DRAIN ③ SOURCE

■ Outline Drawings [mm]



Description	Symbol	Characteristics	Unit	Remarks
Duain Course Voltage	V <sub>DS</sub>	600	V	
Drain-Source Voltage	V <sub>DSX</sub>	600	V	V <sub>GS</sub> = -30V
Continuous Drain Current	I <sub>D</sub>	±10	A	
Pulsed Drain Current	IDP	±40	A	
Gate-Source Voltage	V <sub>GS</sub>	±30	V	
Repetitive and Non-Repetitive Maximum AvalancheCurrent	IAR	10	A	Note*1
Non-Repetitive Maximum Avalanche Energy	Eas	416	mJ	Note*2
Repetitive Maximum Avalanche Energy	Ear	16.5	mJ	Note*3
Peak Diode Recovery dV/dt	dV/dt	4.4	kV/μs	Note*4
Peak Diode Recovery -di/dt	-di/dt	100	A/µs	Note*5
Mayimum Bawar Biosination	PD	1.67	W	Ta=25°C
Maximum Power Dissipation		165	VV	Tc=25°C
Oneveting and Stavene Temperature venue	Tch	150	°C	
Operating and Storage Temperature range	Tstg	-55 to + 150	°C	
Isolation Voltage	Viso	2	kVrms	t = 60sec, f = 60Hz

#### ● Electrical Characteristics at Tc=25°C (unless otherwise specified)

Description	Symbol	Conditions		min.	typ.	max.	Unit	
Drain-Source Breakdown Voltage	BVDSS	I <sub>D</sub> =250μA, V <sub>GS</sub> =0V		600	-	-	V	
Gate Threshold Voltage	V <sub>GS</sub> (th)	In=250µA, Vos=Vos	I <sub>D</sub> =250µA, V <sub>DS</sub> =V <sub>GS</sub>		3.0	3.5	V	
Zero Gate Voltage Drain Current		V <sub>DS</sub> =600V, V <sub>GS</sub> =0V	T <sub>ch</sub> =25°C	-	-	25	μA	
	Ipss	V <sub>DS</sub> =480V, V <sub>GS</sub> =0V	T <sub>ch</sub> =125°C	-	-	250		
Gate-Source Leakage Current	Igss	V <sub>GS</sub> =±30V, V <sub>DS</sub> =0V		-	10	100	nA	
Drain-Source On-State Resistance	R <sub>DS</sub> (on)	I <sub>D</sub> =5A, V <sub>GS</sub> =10V		-	0.675	0.79	Ω	
Forward Transconductance	<b>g</b> fs	I <sub>D</sub> =5A, V <sub>DS</sub> =25V		6	12	-	S	
Input Capacitance	Ciss	V <sub>DS</sub> =25V		-	1800	2700		
Output Capacitance	Coss	V <sub>GS</sub> =0V		-	140	210	pF	
Reverse Transfer Capacitance	Crss	f=1MHz		-	10.5	16	1	
Turn-On Time	td(on)	V <sub>cc</sub> =300V V <sub>dS</sub> =10V I <sub>D</sub> =5A		-	20	30	ns	
	tr			-	9	13.5		
	td(off)			-	100	150		
Turn-Off Time	tf	R <sub>G</sub> =15Ω		-	18	27	1	
Total Gate Charge	QG	Vcc=300V ID=10A		-	47	70.5		
Gate-Source Charge	Qgs			-	10.5	16	nC	
Gate-Drain Charge	Q <sub>GD</sub>	V <sub>GS</sub> =10V		-	13.5	20	1	
Avalanche Capability	lav	L=3.05mH, Tch=25°C		10	-	-	Α	
Diode Forward On-Voltage	V <sub>SD</sub>	I <sub>F</sub> =10A, V <sub>GS</sub> =0V, T <sub>ch</sub> =25°C		-	0.86	1.30	V	
Reverse Recovery Time	trr	I <sub>F</sub> =10A, V <sub>GS</sub> =0V		-	0.51	-	μS	
Reverse Recovery Charge	Qrr	-di/dt=100A/µs, Tch=25°C		-	5.4	-	μC	

#### Thermal Characteristics

Description	Symbol	Test Conditions	min.	typ.	max.	Unit
Thermal resistance	Rth (ch-c)	Channel to Case			0.758	°C/W
	Rth (ch-a)	Channel to Ambient			75.0	°C/W

Note \*1 : Tch≤150°C

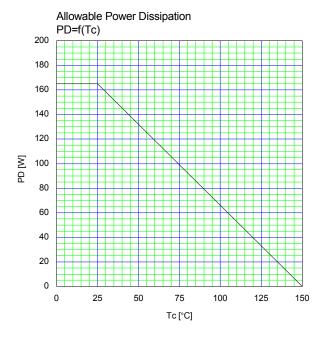
Note \*2 : Stating Tch=25°C, Ias=4A, L=47.7mH, Vcc=60V, Rc=50Ω
Eas limited by maximum channel temperature and avalanche current.
See to 'Avalanche Energy' graph.

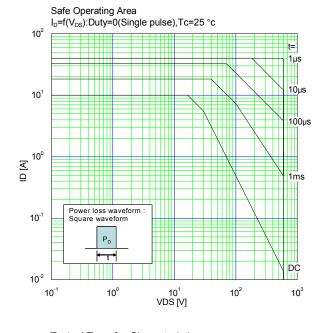
Note  $^{\star}3$  : Repetitive rating : Pulse width limited by maximum channel temperature

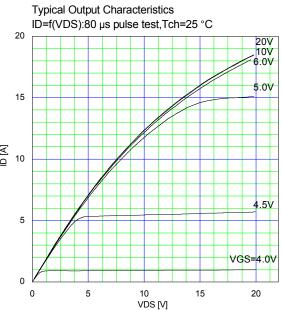
See to the 'Transient Themal impeadance' graph.

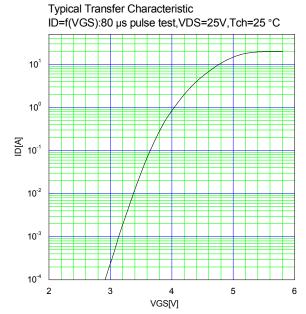
Note \*4 : I₅≤-I₀, -di/dt=100A/μ₅, Vcc≤BV₀ss, Tch≤150°C.

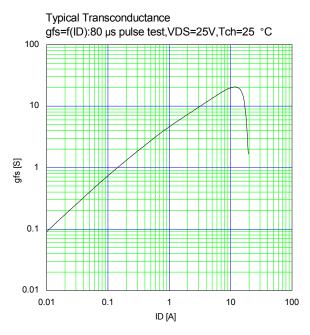
Note \*5 : I₅≤-I₀, dv/dt=4.4kV/μ₅, Vcc≤BV₀ss, Tch≤150°C.

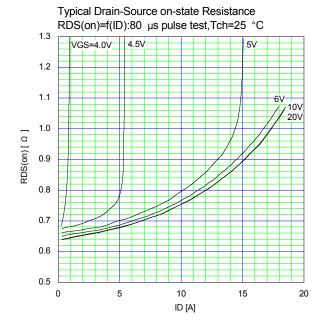




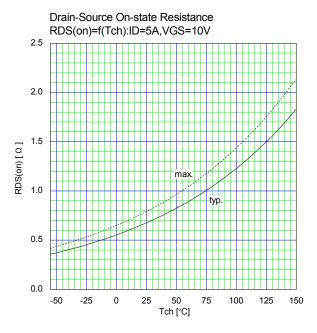


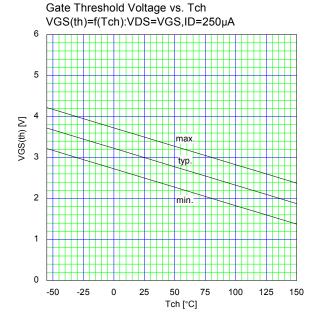


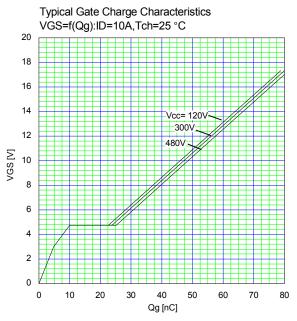


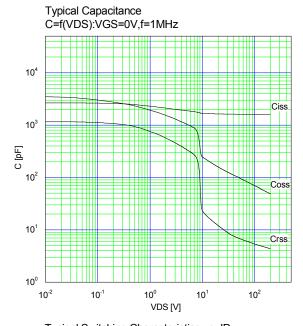


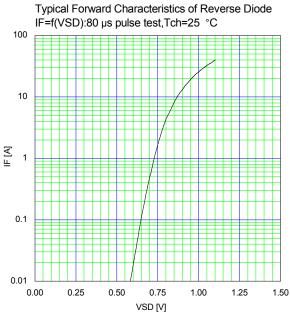
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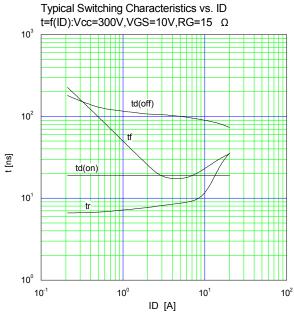


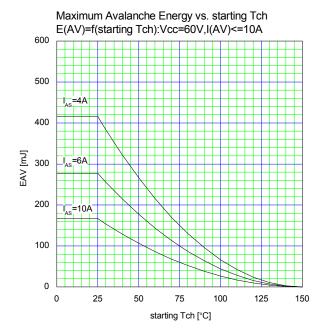


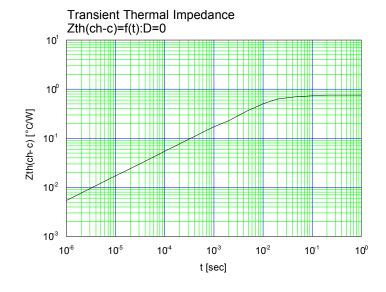












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